

Product / Process Change Notification



N° 2015-086-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Implementation of 300mm wafer diameter, capacity extension and conversion to halogen free mold compound for selected 600V C6 CoolMOS™ DPAK/IPAK products.

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **07. January 2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
- This PCN includes a **Product Discontinuation Notice** (JEDEC STANDARD "JESD48") on page 5.

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

In case the customer rejects this PCN this PCN shall be considered a product discontinuation notice (PD).

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SUBJECT OF CHANGE:

- Implementation of 300mm wafer diameter.
- Extension of wafer production capacity.
- Conversion to halogen free mold compound for DPAK/IPAK products at subcontractor Nantong Fujitsu Microelectronics Co., Ltd. (NFME), Nantong, China and IFX Malacca, Malaysia.

PRODUCTS AFFECTED:

TYPE	SP N°	OPN	Package
IPD60R2K0C6	SP000799132	IPU60R2K0C6BKMA1	PG-TO252
IPD60R3K3C6	SP000799130	IPD60R3K3C6BTMA1	PG-TO252
IPU60R2K0C6	SP000931528	IPU60R2K0C6BKMA1	PG-TO251

REASON OF CHANGE:

Capacity Extension for 300mm wafer production and Introduction of halogen free DPAK/IPAK at subcontractor Nantong Fujitsu Microelectronics Co., Ltd. (NFME), Nantong, China and IFX Malacca, Malaysia.

DESCRIPTION OF CHANGE:

	<u>OLD</u>	<u>NEW</u>
<ul style="list-style-type: none"> ■ Wafer production site with wafer diameter: 	<p>Infineon Technologies Austria AG, Villach, Austria (200mm)</p> <p>Infineon Technologies (Kulim) Sdn. Bhd., Malaysia (200mm)</p>	<p>Infineon Technologies Austria AG, Villach, Austria (200mm and 300mm)</p> <p>Infineon Technologies (Kulim) Sdn. Bhd., Malaysia (200mm)</p> <p>Infineon Technologies Dresden GmbH, Germany (300mm)</p>
<ul style="list-style-type: none"> ■ Halogen Free Production: 	<p>Non halogen free production at IFX Malacca, Malaysia and subcontractor NFME, China.</p>	<p>Halogen free production at IFX Malacca, Malaysia and subcontractor NFME, China.</p>

PRODUCT IDENTIFICATION:

1. Internal traceability: assured via baunumber, lot number and date code
2. External traceability: new SP number for Halogen free products.
3. Lotnumber printed on Barcode Product Label:
 - VE**xxxxxx = IFX Villach, 200mm production
 - 1E**xxxxxx = IFX Kulim, 200mm production
 - PF**xxxxxx = IFX Kulim, 200mm production
 - ZF**xxxxxx = IFX Dresden, 300mm production
 - VF**xxxxxx = IFX Villach, 300mm production

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4. Halogen Free Logo printed on Barcode Product Label (example):



5. Marking Pattern for DPAK/IPAK, comparison

Non Halogen free: G + 2 + 3 digits

Halogen free: H + 2 + 3 digits

Subcon NFME
Non Halogen Free



Subcon NFME
Halogen Free



Malacca
Non Halogen Free



Malacca
Halogen Free



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TIME SCHEDULE:

■ Final qualification report:	Available	
■ First samples available:	Available	
■ Intended start of delivery:	01-December-2015 or earlier date based on customer approval	
■ Last order date of unchanged product:	31-May-2016	See page 5
■ Last delivery date of unchanged product:	30-November-2016	See page 5

ASSESSMENT:

Product Quality and Reliability remains the same as proven by product and wafer technology qualification.
Product data sheets with all electrical characteristics remain unchanged.
Processes are optimized to meet identical product performance according to the existing Infineon specifications.

DOCUMENTATION:

NA

PRODUCT DISCONTINUATION

PD15086



referring to PCN N° 2015-086-A

■ Last order date of unchanged product:	2016-05-31
■ Last delivery date of unchanged product	2016-11-30

DISCONTINUED				NEW (REPLACEMENT)			
Device	SP N°	OPN	Package	Device	SP N°	OPN	Package
IPD60R2K0C6	SP000799132	IPD60R2K0C6BTMA1	PG-TO252	IPD60R2K0C6	SP001117714	IPD60R2K0C6ATMA1	PG-TO252
IPD60R3K3C6	SP000799130	IPD60R3K3C6BTMA1	PG-TO252	IPD60R3K3C6	SP001117718	IPD60R3K3C6ATMA1	PG-TO252
IPU60R2K0C6	SP000931528	IPU60R2K0C6BKMA1	PG-TO251	IPU60R2K0C6	SP001399934	IPU60R2K0C6AKMA1	PG-TO251

If you have any questions, please do not hesitate to contact your local Sales office.